

Multi-Objective Optimization of Solar Cells Thermal Uniformity Using Combined Power of ANSYS Multi-Physics, modeFrontier and eArtius

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Current Computational Design Process

Corp ::

8 threads i7 CPU

Computer —

Q Core

Shared L3 Cache

240 cores TESLA Graphic Processing Unit GPU (x2)



fastest component

and grows exponentially faster

Human Thinking

and Analysis

slowest component

(meetings, reviews, alignments, cancelations)

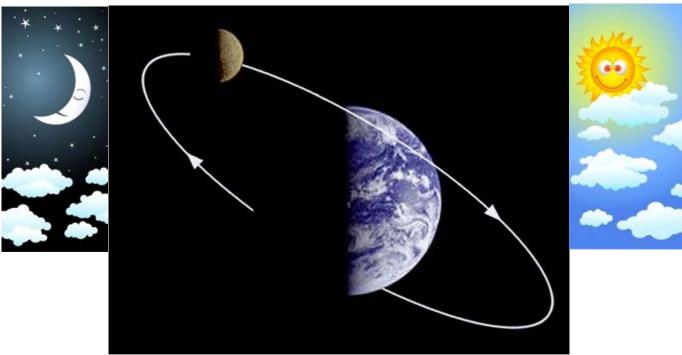
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Ingenious

Solutions

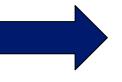
Morning after Effect

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10 times CPU speed improvement

10 hours overnight job or



Makes no difference at 8 AM in the morning

1 hour overnight job

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Human can not match computer in repetitive tasks and consistency. Assuming computational problem takes 30 minutes of CPU time, then in one day (between 8AM to 8 AM) computer is capable of producing 48 design evaluations, with 144 designs completed in just 3 work days.

Coupled with multi-processing capability of i7 workstation this number can easily be multiplied by factors ranging from two to six.

Computer will work during the weekend; it will work when user is on vacation, on sick leave or on business trip.

-"Nothing to run" as single user <u>mental bottleneck</u> is reached, computer resource is

underutilized, software is idle.



\$1,299.99 after \$400 OFF Dell XPS 8300 Desktop Core i7-2600 3.4GHz Microsoft Office Home & Student 2010 Blu-ray ROM Wireless Keyboard & Mouse 1GB AMD Radeon HD 6450 Graphics 19-in-1 Media Card Reader Item # 582103 Rated 文公介 @ (out of 10 reviews) Share this Product 중 知 世 \$1,299.99 Shipping & Handing included

+ ADD TO CAR

Personal "super computer" cost is now inconsequential for the bottom line.

Software cost sky-rocketed, and its ROI and utilization efficiency is now most important.

Computer needs algorithmic analogy of "human brain" to self-guide solution steps.

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New paradigm of <u>multi-objective computational design</u> is now being born.

No longer designer needs to approach it through "trial-and-error" simulations, but can rather use "artificial intelligence" of optimization method to automatically seek and to find best combination of input parameters (design). Depending on problem size (CPU time) this process can take from minutes to weeks.

However, now engineer can view tens and hundreds of possible solutions, automatically singling first truly best designs and then evaluate design trade-offs between conflicting objectives (Pareto Frontier).



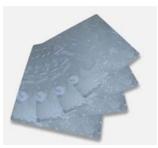
Heating Challenge to Address



A Revolution in Value for the Solar Industry

Great number of companies and technologists in Silicon Valley are now focused on developing lower-cost processing methods and capital equipment to manufacture solar cells. It is typically done through a variety of high temperature thermal processes, where temperature uniformity is the most critical factor.

Using ANSYS Workbench we developed lamp heating surface-to-surface thermal conduction-radiation model for simultaneous transient multi-step heat-up of silicon substrates. Lamp locations, lamp to substrate distances, lamp dimensions, lamp power and its distribution are being optimized to achieve industry standard ±5 degrees thermal uniformity requirement.













http://www.intevac.com/solar-process-sources

Minimize thermal variation across single substrate and across a group of substrates during radiant heating stage (TempDiff)

Operate in required process temperature window, T-dev1<Top<T+dev2

Optimization Formulation

Top=400 deg.C

min (TempDiff) *min* abs(Tmax-Top) & *min* abs(Tmin-Top)

Constraints to determine design feasibility:

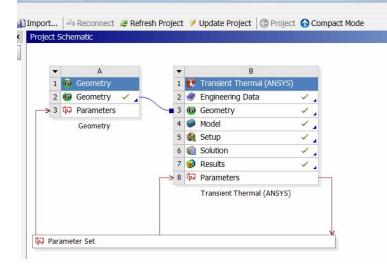
T<Tmax.constr & T>Tmin.constr, where

Tmin.constr= Top-dev1, Tmax.constr=Top+dev2

If dev1 and dev2 are small, then optimization problem is very restrictive.

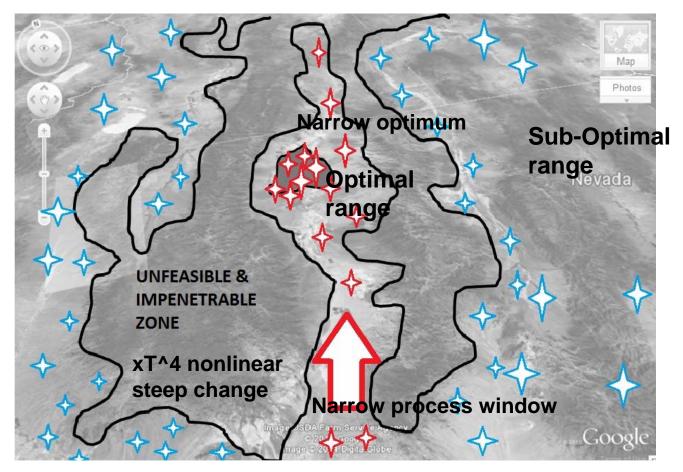
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ANSYS WB Formulation:



ΝΤΕΥΔΟ

Problem Analogy – Hidden Valley in the Mountains



Gradient method requires path, to enter narrow optimal range (due to nonlinearity) it requires guidance or coincidence. Guidance comes from the previous history (steps taken before, gradients) and coincidence from DOE or random mutations.

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In our study we used modeFrontier as optimization enabling (Scheduler) and statistical data post-processing tool and eArtius multi-objective optimization methods plug-in tool to guide continuous process of selecting better input variables to satisfy multiple design objectives.

This process follows <u>"fire and forget</u>" principle and relies on combination of self-guiding gradient methods with genetic selection (crossover and mutation). Algorithm automatically use current results to best select inputs for the next design decision step. Gradient based computer thinking combines advantages of precise analytics with human like decision making (selecting roads that lead to improvement, avoiding weak links, pursuing best options, connecting dots). Genetic component guides selection and allows to jump out if local improvements can not be found.





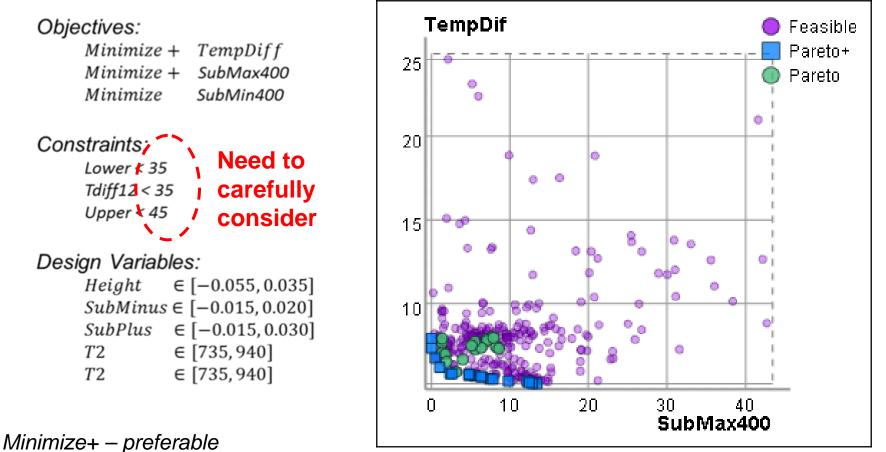


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Thermal System Optimization Task Formulation

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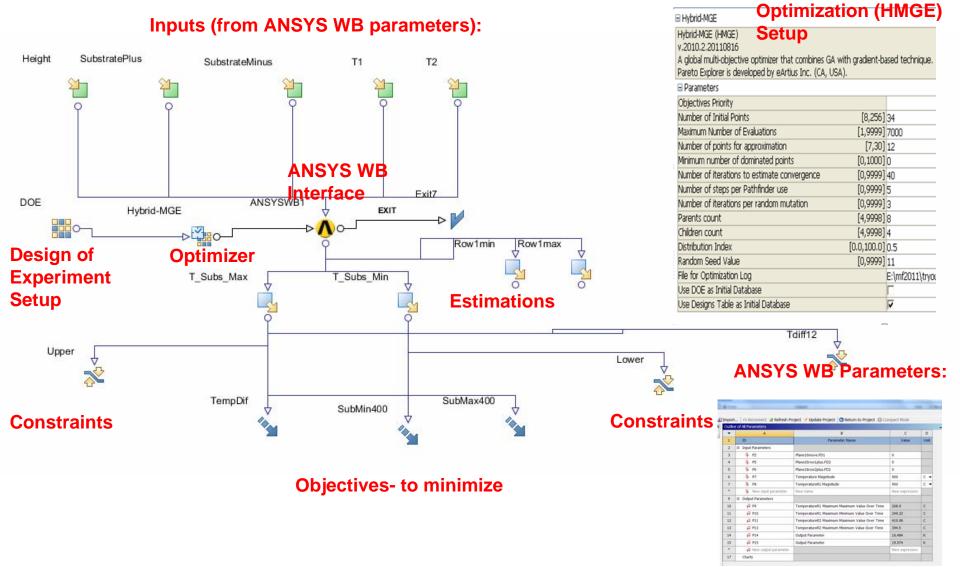


objectives Minimize – regular objective

278 feasible designs of 317 evaluations18 Pareto+ designs of 35 Pareto optimal designs

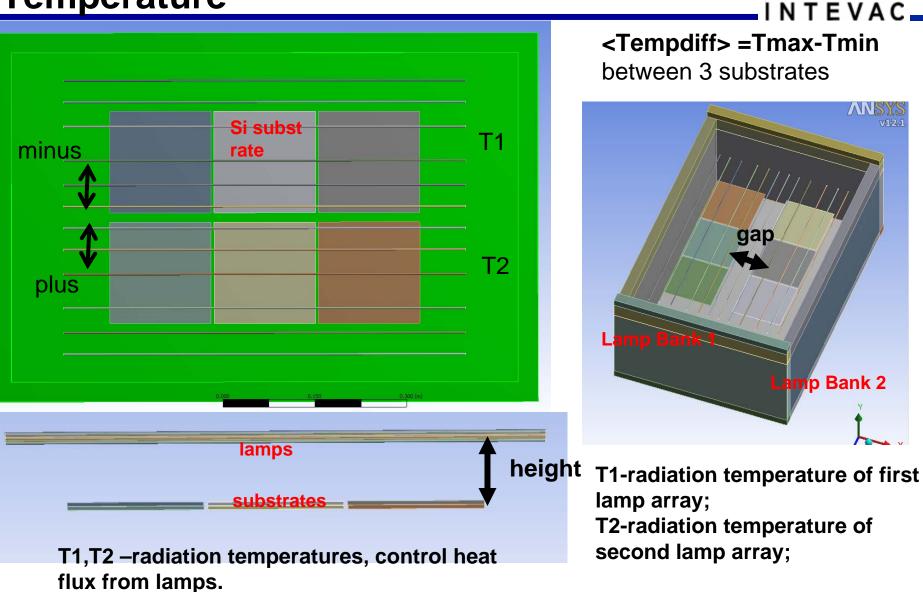
Optimization Flow Chart in ModeFrontier

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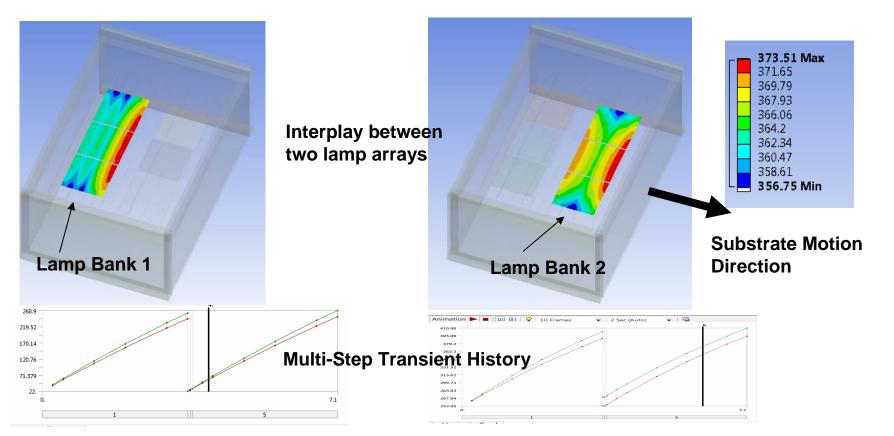


Problem Parameters – Geometry and

Temperature



Thermal Heating (Radiation) Solution



Transient Heating Scenario: Row1 of substrates is first heated by Lamp Bank1, then these Substrates moved to Lamp Bank2 and get heated again till desired Top=400 deg.C is reached. Simultaneously, new substrates with T=Tambient populate Row1 and get heated. Thus, Row1 heats from 22 to 250 deg.c and Row 2 from 250 to 400 deg.C.

at time t=3.5 sec Row1 T is reset at 22 deg.C; Row2 T is reset at 250 deg.C. at time t=0 sec Row1 T is set at 22 deg.C; Row2 T is set at 250 deg.C.

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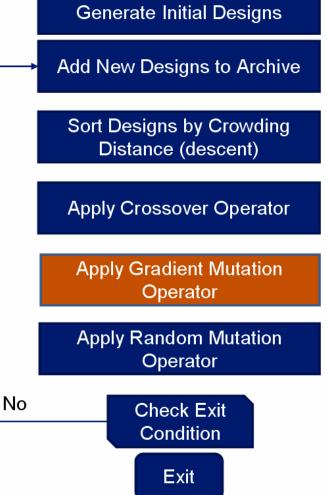
but in addition to a standard random mutation operator, HMGE uses a gradient mutation operator, which improves convergence.

Thus, random mutation helps find global Pareto frontier, and gradient mutation improves convergence to the Pareto frontier. In such a way HMGE algorithm combines advantages of both gradient-based and Genetics-based optimization techniques: it is as fast as a pure gradient-based algorithm, and is able to find the global Pareto frontier with robustness similar to genetic algorithms (GA).

functions considered in a multi-dimensional domain is

utilized in this study. This hybrid algorithm relies on genetic variation operators for creating new solutions,

Hybrid Multi-Gradient Explorer (HMGE) algorithm



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www.eartius.com

Dynamically Dimensioned Response Surface

DDRS Method is a fast and scalable algorithm for estimating gradients

DDRSM can be used as an element for designing any gradient-based optimization algorithms, including hybrid algorithms.

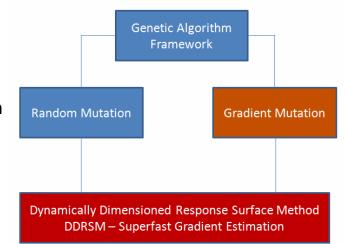
How DDRSM operates:

- Automatically determines the most significant design variables for each response variable separately
- Builds local approximations for each response based only on the most significant design variables
- Estimates gradients analytically based on local approximations
- Repeats the above sequence on each optimization step

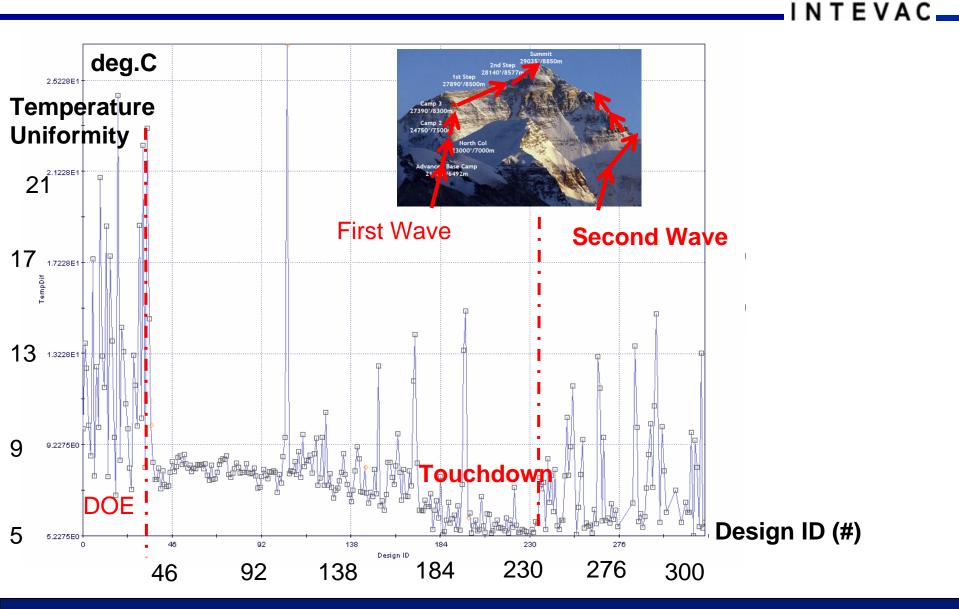
DDRSM Benefits:

- Equally efficient and accurate for any task dimension
- Requires just 0-7 model evaluations regardless of task dimension
- Fast— it builds a local approximation in 10-30 milliseconds
- Automatic and hidden from users
- Eliminates necessity in global response surface methods
- Eliminates necessity in a sensitivity analysis

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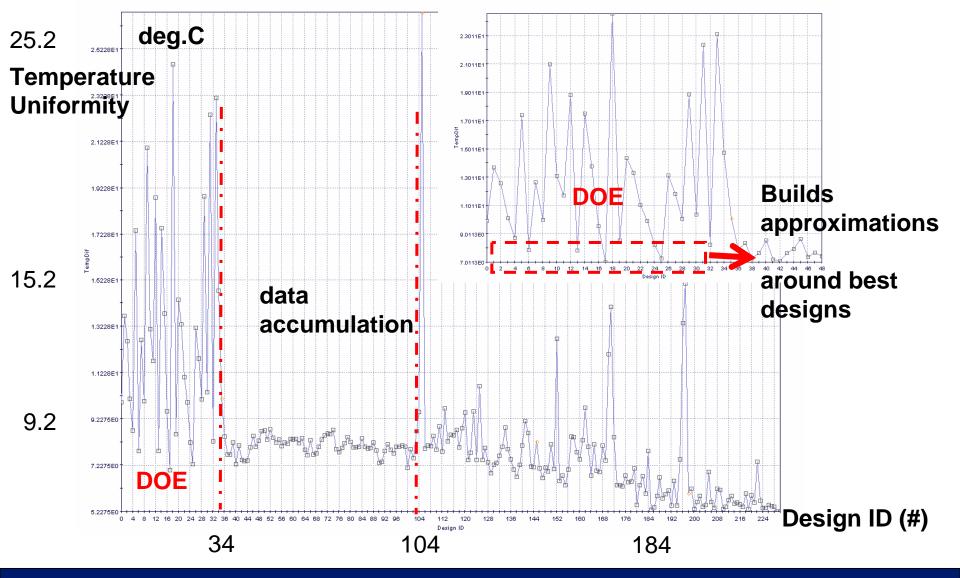
"Fire And Forget" Solution Process - HMGE



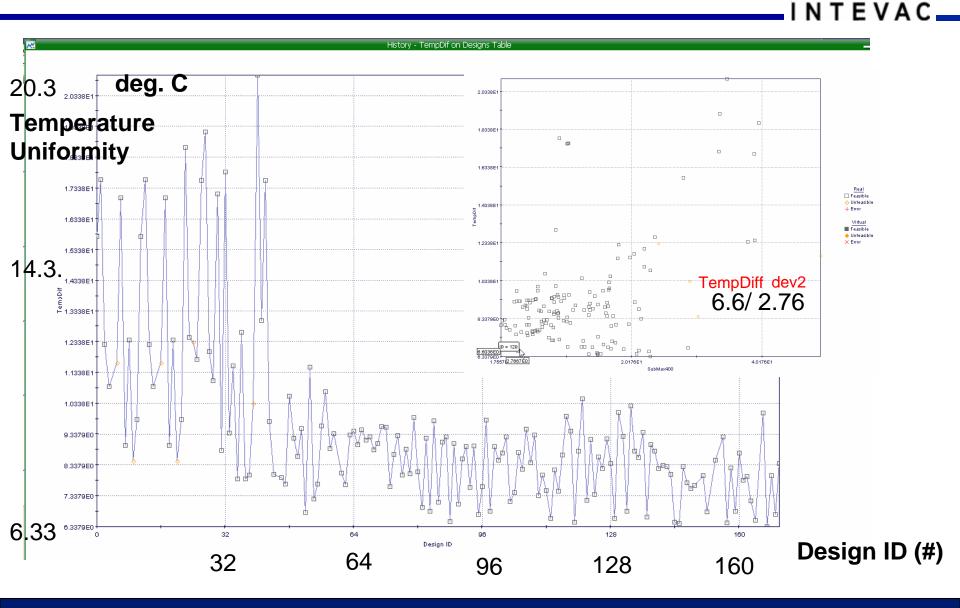
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HMGE Optimization of Temperature Difference

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Optimization Using NSGAII modeFrontier

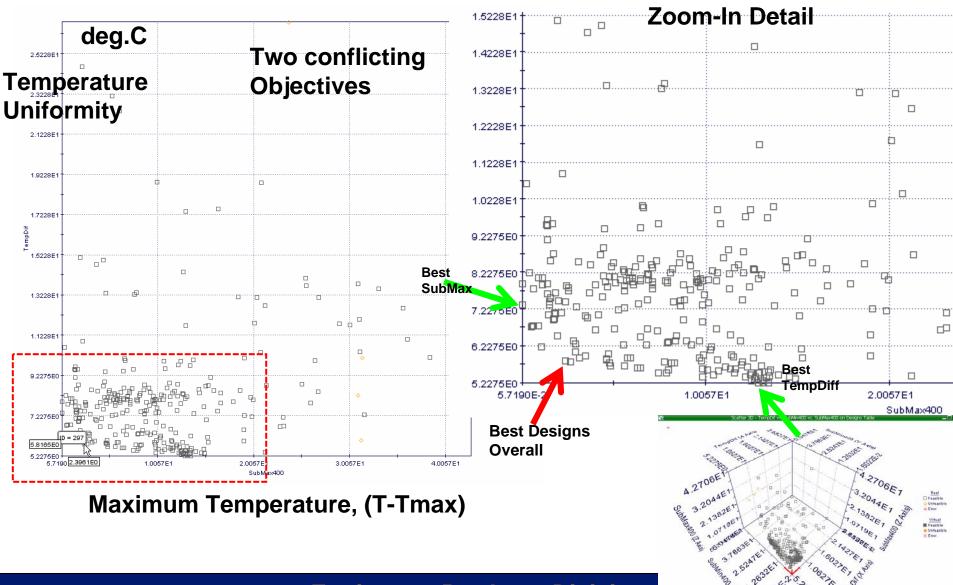


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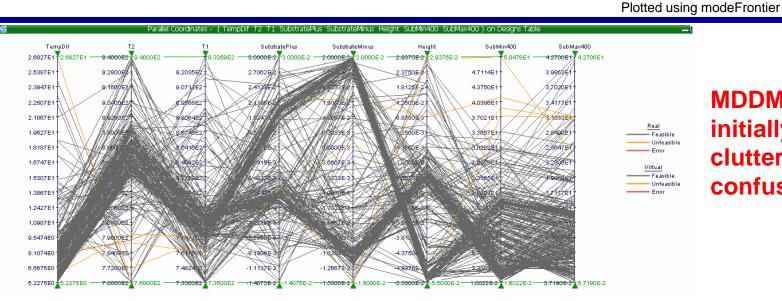
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Optimization Solution: Pareto Front

Plotted using modeFrontier



Multi-Design Decision Making in mFrontier





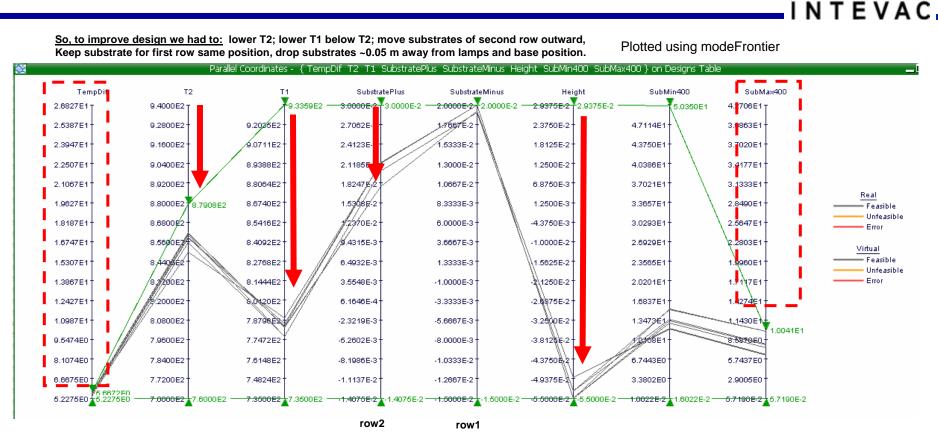
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~ ~ ~ ,	Para	allel Coordinates - { Te	empDif T2 T1 Substrati	ePlus SubstrateMinus He	ight SubMin400 Sul	bMax400 } on Designs Ta	ble	
TempDif	Т2	T1	SubstratePlus	SubstrateMinus	Height	SubMin400	SubMax400	
2.6827E1	9.4000E2	9.33591	E2 - 3:0000E-2 3.0000E-	2 - 2.0000E-2 - 2.0000E-2	2.9375E-2 2.9375E	-2 5.0478E1	4.2700E1 4.2706E1	
2.5387E1-	9.2800E2 -	9.2025E2	2.7062E-2-	19 11 19	2.3750E-2	4.7114E1-	3.9863E1-	
2.3947E1	9.1600E2	9.0711E2	2.4123E-2	6583E-2-	1.8125E-2-	4.3750E1	3.7020E1	
2.2507E1	9.0400E2	8.9388E2	2.1185E-2	1.3000E-2	1.2500E-2	4.0386E1	3.4177E1	
2.1067E1	8.9200E2	8.8064E2	1.82475	1.0667E-2	6.8750E-3	3.7021E1	3.1333E1	Real
1.9627E1	8.8000E2 8.7908E2	2 8.6740E2	1.54	8.3333E-3	1.2500E-3 -	3.3657E1	2.8490E1	Feasible
1.8187E1-	8.6800	8.5416E2-	1 ؀-2	6.0000E-3-	-4.3750E-3	3.0293E1-	2.5647E1	Unfeasible Error
1.6747E1-	8.560057+	8.4092E2	9915E-3	3.6667E-3	-1.0000E-2-	2.6929E1	2.2803E1	Virtual
1.5307E1	8 440	8.2768E2	6.4932E-3	1.3333E-3	1.5625E-2	2.3565E1		Feasible
1.3867E1	8 152	8.1444E2	3.5548E-3	. 0000E-3	1250E-2 -	2.0201E1	1.7117E1	Error
1.2427E1	2000E2	UNDER	6.1646E-4-	-3.3833E-3-	-2. 75E-2-	1/0857	CONTRACTOR OF CONTRACTOR	
1.0987E1	\$.0800E2-	7.0 162	-2.3219E-3	-5.666XE-3	-3.2s 1E-2 -		1.1430.011	
9.5474E0	7.9600E2-	7.7472E3	-5.2602E-3	-8.0000E-8-	-3.812 2-		8.557950	
8.1074E0	7.8400E2	7.6148E2	-8.1986E-3	-1.0333E-2	-4.37501	6.7443E0	5.7437E0	
6.6675E0	7.7200E2 *	7.4824E2	-1.1137E-2	-1.2667E-2	4.9375E-3	3.3802E9	2.000650	
5.2275E0 5.2275		2	E2 -1.4075E-2	-2 -1.5000E-2	-5.5000E-2 -5.5000F	E-2 - 1.0022E-2 1.6022E-2	5.7190E-2 5.7190E-2	

Tempdiff is narrowed to Less than 6 deg.C and suddenly way more clarity

Best Designs Selected -MDDM



<Tempdiff> is narrowed to less than 6 deg.C and allowable deviation from maximum temperatuire reduced to 10 deg.C. Only several acceptable designs are left to consider.

Scatter Optimization Summary Matrix

Plotted using modeFrontier

Scatter Matrix - Height: SubstrateMinus: SubstratePlus: T1: T2: TempDif: SubMin400: SubMax400 on Designs Table SubstratePlus Τ1 T2 TempDif SubMin400 SubMax400 Height SubstrateMinus Heiaht 1.1 SubstrateMinus SubstratePlus 0.616 Τ1 0.095 -0.020 -0.065 Т2 -0.085 -0.106 -0.024 -0.183 Decrease Drop T1 increase increase increase height T2,0 268 -0.251 TempDif 0.605 -0.368 0.525 move substrates away from lamps SubMin400 -0.202 0.433 0.302 -0.080 -0.483 0.115 SubMax400 0.581 0.009 0.145 0.143 0.278 0.079 0.251 **Operating Max** No effect Negative No effect Correlated Temperature Correlated Effect

Red color affects positively;

Blue color-negatively. Increase in Tdiff means that design is worse, as we want to minimize TempDiff.

SubMax400 – deviation above 400 deg. C=> smaller=better.

SubMin400 – deviation below 400 deg.C => smaller= better.

Negative Height moves substrates down, away from base position and away from lamps.

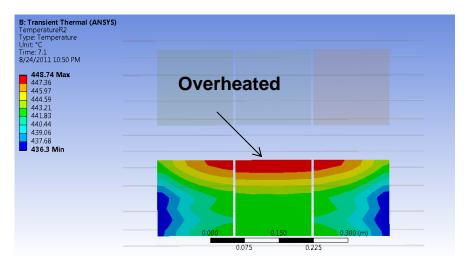
Positive Height moves substrates up, away from base position, closer to lamp.

SubstrateMinus-Row1, Positive moves inward, negative outward

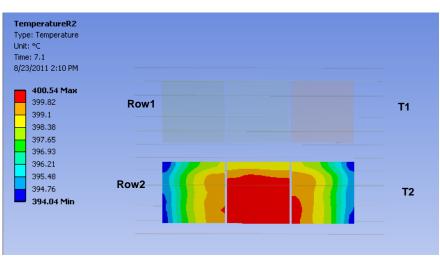
SubstratePlus-Row2, positive moves inward, negative outward

Baseline Design vs. Optimized

Baseline Hardware Design, all zero deviations, T1=T2=900 deg



deltaT=12.44 subMax=dev2=48.7 deg.C (desired 10 deg or less) One of several optimized Pareto+ designs



TempDiff ~ 6 deg. C subMax=dev2= 0.54 deg.C

T1 dropped below T2, this way less overheating of the center zone (top edge of the substrate on the picture)

Row2 Substrates moved up (away from their more central position)

- that allows to shift temperature peak from the center zone (substrate top edge) into the middle of substrate)

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Going Head-to-Head with Human

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In head-to-head competitions best "human guided" (case-by-case) studies resulted in system design with ±10-20 deg.C thermal uniformity and took several weeks to accomplish, while computer optimization based approach allowed to quickly yield multiple solutions capable of reaching ± 3 deg. C. It took only two 24 hour cycles for CPU to "independently" accomplish this task.

But most importantly, multi-objective optimization analysis provided unique insights into system behavior and lead to innovative enabling design solutions. Statistical analysis of designs provided confidence that we found solutions that are truly best.

Thus, we can conclude that "Optimization Equals Innovation".

Further improvement in Design Modeler is required to allow more flexible parameterization of geometry setup, exploring ANSYS SpaceClaim can help.

Conclusion: Optimization = Innovation





modeFrontier ANSYS eArtius

WorkBench



Authors are thankful to ESTECO engineers for developing eArtius HMGE modeFrontier plug-in; to Alberto Bassanese (ESTECO) for introducing and helping with modeFrontier; to ANSYS Distributor in Bay Area Ozen Engineering <u>www.ozeninc.com</u> (Kaan Diviringi, Chris Cowan and Metin Ozen) for help and dedicated support with ANSYS Workbench model development and integration with modeFrontier.